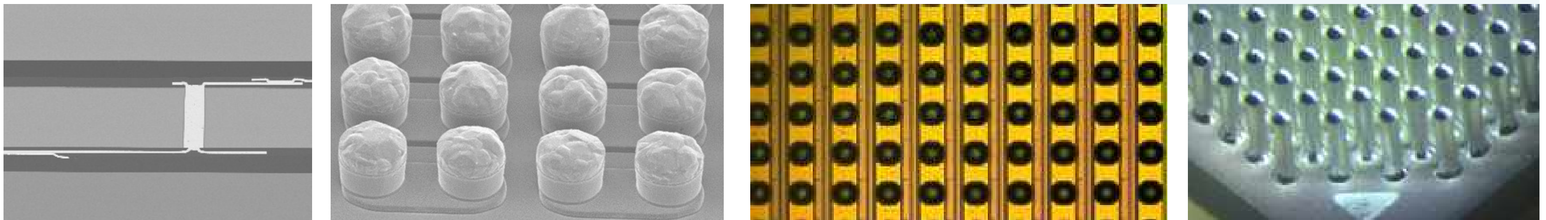
Advanced Interconnect Technology



Innovative Next-Gen Packaging Solutions

Micross Advanced Interconnect Technology offers advanced packaging and 3D integration solutions that enable higher-performance systems with decreased size, weight & power (SWaP).

Micross AIT provides a wide variety of advanced interconnect technologies for realizing your next-generation electronic systems inclusive of:

-Flip-chip and wafer-level packaging

-Through-silicon vias (TSV)

-Through glass vias (TGV)

-High-density (fine pitch) Interconnects

-Fabrication of Si or glass interposers

Micross AIT houses an ITAR-registered, state of-the-art microfabrication facility that allows us to provide development, custom prototyping and small volume production services for our customers.

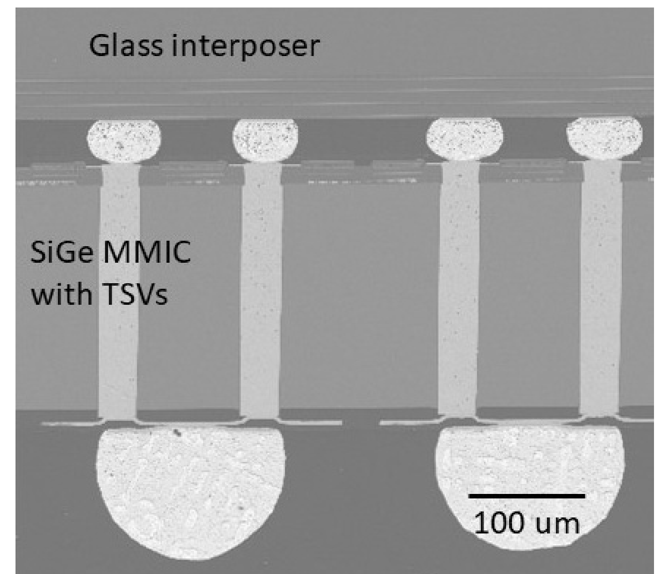
Providing Integration and Advanced Packaging Solutions across a Vast Array of Applications

Microsystems are the building blocks of information technology and include components such as integrated circuits (ICs), photonic and optoelectronic ICs and microelectromechanical systems (MEMS). Microsystem integration involves technologies for connecting the individual components into multifunctional electronic systems.

Micross AIT has been at the forefront of the development of such interconnect and packaging technologies for more than 25 years, making them accessible to external organizations for a wide variety of advanced and low-volume applications. We provide application-based solutions for government and industry clients, as well as collaborate with commercial and academic partners in technology areas such as high-performance sensor and actuator arrays, biomedical devices and high-performance computing.

Our integration and packaging technologies include:

- 3D integration technology: TSV, TGV, Si interposers, 3D IC
- Advanced interconnect and packaging technologies:
  Solder bumping, Cu pillar, Cu-based microbumps, Assembly
- Column Grid Array (CGA) Technology: provides greatly improved reliability over Ball Grid Array interconnects for ceramic-packaged devices for Aerospace and other hi-reliability applications.
- Microstructure fabrication and packaging:
  Monolithic integration, vacuum microelectronics, wafer-level vacuum packaging



ABOUT MICROSS

Micross (www.micross.com) is the global one-source provider of Bare Die & Wafers, Advanced Interconnect Technology, Custom Packaging & Assembly, Component Modification Services, Electrical & Environmental Testing and Hi-Rel Products to manufacturers and users of semiconductor devices. In business for over 40 years, our extensive hi-reliability capabilities serve the Aerospace & Defense, Space, Medical and Industrial markets. Micross possesses the sourcing, packaging, assembly, engineering, test and logistics expertise needed to support an application throughout its entire program cycle.

If you're facing miniaturizing and integration challenges for your multifunctional systems, contact us to learn more about how we can help you obtain the best performance from your systems.

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